I HEREBY CERTIFY THAT THIS CORRESPONDENCE IS BEING DEPOSITED ON JANUARY 27, 1998, WITH THE UNITED STATES POSTAL SERVICE AS FIRST CLASS MAIL IN AN ENVELOPE ADDRESSED TO: ASSISTANT COMMISSIONER FOR PATENTS, WASHINGTON, D.C. 20231.

Dugum Wall



PATENT
DOCKET NO. 420099-654
LSI REF. P-2880/1D

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF

MIKE LIANG

SERIAL NO.: 08/909,312

FILED: AUGUST 14, 1997

ENTITLED: METHOD FOR DISTRIBUTING CONNECTION PADS ON A SEMICONDUCTOR

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GROUP ART UNIT: 1104

EXAMINER:

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CHANGE OF ADDRESS

Sir:

Please direct all further communications relative to the above-captioned divisional appplication as follows:

OPPENHEIMER WOLFF & DONNELLY LLP

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Respectfully submitted,

Dated: January 27, 1998

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